

PCN Number:	20230328002.1			PCN Date:	March 29, 2023
Title:	Qualification of CDAT as an additional Assembly site for the TPS22971YZPR/T				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Jun 27, 2023	Sample Requests accepted until:	April 29, 2023*		
*Sample requests received after April 29, 2023 will not be supported.					
Change Type:					
☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
		☐		☐	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly and test site for the TPS22971YZPR/T. There are no construction differences between the 2 sites.					
Reason for Change:					
Supply continuity					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS		REACH		Green Status	
☒ No Change		☒ No Change		☒ No Change	
				IEC 62474	
				☒ No Change	
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
Clark	QAB	PHL	Angeles City, Pampanga		
CDAT	CDA	CHN	Chengdu		
Sample product shipping label (not actual product label)					
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750					
					
(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO: USA (22L) AS0: MLA (23L) ACO: MYS					

Product Affected:

TPS22971YZPR

TPS22971YZPT

TI Information
Selective Disclosure**Qualification Report**
Approve Date 09-March-2023**Qualification Results****Data Displayed as: Number of lots / Total sample size / Total failed**

Type	#	Test Name	Condition	Duration	Qual Device: TPS22971YZPR	QBS Reference: TPS22964CZYPR	QBS Reference: TPS22964CZYPR	QBS Reference: SH6968BAA0PAPG4
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/426/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	3/15/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/PASS	1/PASS	-
FTY	E6	Final Test Yield	-	-	-	1/PASS	1/PASS	-

- QBS: Qual By Similarity
- Qual Device TPS22971YZPR is qualified at MSL1 260C
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- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2203-034

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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